CIRCUIT FOIL AND MITSUI MINING & SMELTING SIGN PATENT LICENSE AGREEMENT ON PRINTED WIRING BOARD

April 1st, 2020

CIRCUIT FOIL LUXEMBOURG and MITSUI MINING & SMELTING CO., LTD have reached a global patent license agreement regarding Mitsui's technology for the fabrication of fine lines using a process called MSAP (Modified Semi Additive Process).

The MSAP process mainly uses much thinner copper foil with carrier, called "MicroThinTM" for Mitsui and "Doublethin" for Circuit Foil.

This agreement authorizes fabricators to use Circuit Foil "Doublethin" for their MSAP process.

Fabienne Bozet, Head of Circuit Foil, says:
"*We are pleased to enter into a global license agreement with Mitsui*".

This License will enable Circuit Foil to increase the sales in the packaging area.

Circuit Foil is a global company with a prestigious reputation for its development of high-quality electrodeposited copper foils for the electronics industry, focused primarily on high-end products.

Mitsui Mining & Smelting Company produces non-ferrous metal such as Zinc and Copper, whose main business is metal smelting, electronic materials and automobile parts. Mitsui Mining & Smelting has developed extremely thin copper foil with carrier foil and they have patents in MSAP.

Living Quality
Targeting Excellence

Fabienne BOZET
Chief Executive Officer

